

Polo scientifico tecnologico

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Precision BGA E2005 Rework System



Features:

- 1. No need for nozzles. No air flow during re-flow process.
- 2. Use non-contact infrared temperature sensor to real-timely measure temperature and achieve closed loop control of temperature during rework process, suitable for lead free process.
- 3. Reflecting foil can be used to reduce thermal transmission to adjacent components.
- 4. Can use process camera to monitor re-flow process of soldering joints during BGA rework process.
- 5. No air flow during the course of BGA re-balling; Nearly 100% successful BGA re-balling.

Specifications:

IR Infrared Rework System

Model IR2005

General Power 1600Watt(max)

Power of Bottom Heater 400W*2=800Watt(Dark Infrared heating plate)

Power of Top Heater 180W*4=720Watt

(Infrared heating tube, wavelength about 2-8 \(\mu \) m)

Size of Top Heater 60*60mm
Size of Bottom Heater 135*250mm

Adjusting Range of Top Heater 20-60mm(X, Y direction both adjustable)

Vacuum Pump 12V/300mA, 0.05Mpa(max)

Top Cooling Fan: 12V/300mA, 15CFM

Laser Alignment Tube 3V/30Ma

Movable Motor 24V DC/100mA

Movable Arm Range 93mm

Max PCB Size 300mm*300mm

LCD Display Window 65.7*23.5mm 16*2 characters

Soldering Station Intelligent Digital Lead Free Soldering Station

Soldering Power 60Watt

Communication RS-232C(connect with PC)
Infrared Temperature Sensor 0-300 (Testing Range)

Outside K-type Sensor Optional
Weight About 13kg

PL Precision Placement System

Model PL2005

Power About 15Watt

Camera 22*10 times magnifying; 12V/300mA

Horizontal resolution: 480 lines; PAL format

Lens Size 40mm*40mm
Size of BGA to be aligned 40mm*40mm

Vacuum Pump 12V/600mA 0.05Mpa(max)

Camera Output Signal Vedio Signal

Weight 22kg

RPC Reflow Soldering Process Camera

Model RPC2005

Power About 15Watt

Camera 22*10 times magnifying; 12V/300mA;

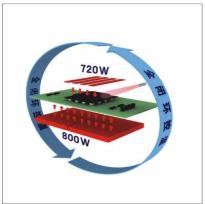
Horizontal resolution: 480 lines; PAL format

Main Parts:

☆Infrared Heating System







Open-type dark infrared heating, non-contact infrared temperature sensor monitors the changes of BGA surface temperature to ensure precise temperature technical window, even heat distribution

and real closed-loop control.





Dark infrared heating technology with 2-8 \(\mu\) m long wave minimizes temperature differences to the largest extent to avoid damages resulted from long dipping, cold soldering and overheating.



Bottom dark infrared ceramic heating plate: 800Watt; The heating plate can preheat PCB evenly to prevent it from being distorted and damaged. Top dark infrared heating tube: 720Watt; Heating area can be adjusted according to sizes of BGA. When process is over, vacuum generated automatically picks up BGA components and return to the original position automatically.

Optical Lens Aligning



Use optical lens to align components. Red top light and white bottom light which brightness can be adjusted. The lens reflects light to make the light of BGA solder ball and PCB solder pat in line with each other.

Through camera of PL, solder ball and solder pat can be clearly viewed in the monitor. By turning the knobs of X, Y axis and component control knob, solder ball displayed in red and solder pat in white can be completely overlapped.

RPC2005



RPC2005 is used to monitor melting, collapsing of solder ball and formation of soldering joint in reflow soldering process. As the aligning arm holds out or draws back, the system automatically

interchange the video signal. RPC can move in all directions to observe from different angles.

Soldering Station



Intelligent digital type: High frequency current heating; Easy to clean soldering pad.

Several types of Combinations



IR2005+Simple PCB Fixture+RPC



IR2005+Simple PCB Fixture



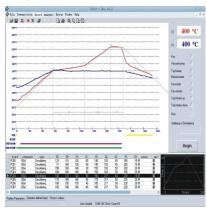
IR2005+Orbital PCB Fixture+RPC



IR2005+Orbital PCB Fixture

IRsoft:

IRsoft is particularly for BGA2005&BGA2015. It can be used to view, record, set and analyze the temperature curve of every reflow soldering process.



- The reflow soldering process of BGA includes 5 phases: preheating, temperature preserving, activating, soldering, cooling. Among which the temperature in three phases(temperature preserving phase, activating and soldering phases) as well as the temperature rising speed are particularly important.
- ♦ Temperature Preserving Phase: Eliminate the temperature differences between components or between PCB and components to protect PCB from being distorted and damaged.
- Activating Phase: Completely activate flux for soldering.

Soldering Phase: The heater heats up continuously. Temperature reaches up to peak value to melt

the BGA solder ball completely and then make it and solder pad well soldered.

♦ TL: Melting temperature of solder. Generally, lead free solder material 217[®]C, lead solder material

183℃.

- ♦ T1: Starting temperature in temperature preserving phase.
- ♦ T2: End temperature in temperature preserving phase.
- ♦T1-T2: Temperature determined according to the size of BGA, thickness of PCB and the quantity

of components on PCB.

- ♦T3: The peak temperature of reflow soldering. Generally, lead free solder material 235 €, lead solder material 200 €.
- ♦ T0: Value temperature, the temperature of bottom heater which allows the top heater to starting heating.
- ♦ TB: The set temperature of bottom heating.
- ♦ Tb: Real-time temperature of bottom heating.
- ♦ Tc: BGA Real-time temperature.
- ♦S1: Heating time rising from T1 to T2.
- ♦ S2: Heating time rising from T2 to T3.
- ♦S3: Prolonged heating time after the temperature reaches T3.

☆Parameter Setting Interface



Set process patameter and upload, download, copy and paste data.

Operator Input Interface



Completely display current temperature of soldering process and operating information of BGA and PCB.

Clamp



For special PCB or those PCBs with sorts of sockets, connectors, clamps of different length can be used to fix them.

The nozzles used to pick up BGA while desoldering and nozzles needed while aligning can be selected according to the sizes of BGA/CSP.

PCB Bottom Supporting Rod

